# IPC 1752

**Form Type**: Distribute  
**Sectionals**: Material Info, Manufacturing Info  
**Subsectionals** : A-D  
**Manufacturing Info**

<table>
<thead>
<tr>
<th>Company Name *</th>
<th>STMicroelectronics</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Response Date</strong> *</td>
<td>2015-09-10</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Contact Name *</th>
<th>Refer to Supplier Comment section</th>
</tr>
</thead>
<tbody>
<tr>
<td>Authorized Representative *</td>
<td>Giovanni Giacopello</td>
</tr>
<tr>
<td>Representative Title</td>
<td>IPO MD CHAMPION</td>
</tr>
<tr>
<td><strong>Representative Phone</strong> *</td>
<td>Refer to Supplier Comment section</td>
</tr>
<tr>
<td><strong>Representative Email</strong> *</td>
<td>Refer to Supplier Comment section</td>
</tr>
</tbody>
</table>

**Supplier Comment**

Online Technical Support - STMicroelectronics :  

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# Uncertainty Statement

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# Legal Statement

**Supplier Acceptance** * : true  
**Legal Declaration** * : Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

---

**Digital Signature**

Signature Not Verified  
Digitally signed by giovanni giacopello  
Date: 2015.09.10  
11:41:08 -02'00
<table>
<thead>
<tr>
<th>Mfr Item Number</th>
<th>Mfr Item Name</th>
<th>Version</th>
<th>Mfr Site</th>
<th>Date</th>
</tr>
</thead>
<tbody>
<tr>
<td>VHWX*0431BB6</td>
<td></td>
<td>A</td>
<td>ZS1A</td>
<td>2015-09-10</td>
</tr>
<tr>
<td>Amount</td>
<td>UoM</td>
<td>Unit type</td>
<td>ST ECOPACK Grade</td>
<td></td>
</tr>
<tr>
<td>10.00</td>
<td>mg</td>
<td>Each</td>
<td>ECOPACK® 2</td>
<td></td>
</tr>
</tbody>
</table>

### Manufacturing Information

<table>
<thead>
<tr>
<th>J-STD-020 MSL Rating</th>
<th>Classification Temp</th>
<th>Nbr of Reflow Cycles</th>
<th></th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>260</td>
<td>3</td>
<td></td>
</tr>
<tr>
<td>bulk Solder Termination</td>
<td>Terminal Plating</td>
<td>Terminal Base Alloy</td>
<td>Comment</td>
</tr>
<tr>
<td>NAC</td>
<td>Tin (Sn), matte</td>
<td>Copper Alloy</td>
<td></td>
</tr>
</tbody>
</table>

### Package Designator

<table>
<thead>
<tr>
<th>Package Designator</th>
<th>Size</th>
<th>Nbr of instances</th>
<th>Shape</th>
</tr>
</thead>
<tbody>
<tr>
<td>SOT</td>
<td>2.85 - 1.5 - 0.9</td>
<td>3</td>
<td>gull wing</td>
</tr>
</tbody>
</table>

Comment: Package: SOT 23 3 LDS; MDF valid for TL431AIL3T
### ROHS directive 2011/65/EU _ July 2011

<table>
<thead>
<tr>
<th>Query</th>
<th>Response</th>
</tr>
</thead>
<tbody>
<tr>
<td>1 - Product(s) meets EU RoHS requirement without any exemptions</td>
<td>true</td>
</tr>
<tr>
<td>2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)</td>
<td>false</td>
</tr>
<tr>
<td>3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)</td>
<td>false</td>
</tr>
<tr>
<td>4 - Product(s) does not meet EU RoHS requirements and is not under exemptions</td>
<td>false</td>
</tr>
<tr>
<td>5 - Product(s) is obsolete, no information is available</td>
<td>false</td>
</tr>
<tr>
<td>6 - Product(s) is unknown, no information is available</td>
<td>false</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Exemption Id.</th>
<th>Description</th>
</tr>
</thead>
</table>

### REACH-15th June 2015

<table>
<thead>
<tr>
<th>Query</th>
<th>Response</th>
</tr>
</thead>
<tbody>
<tr>
<td>1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH</td>
<td>true</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>CategoryLevel_Name</th>
<th>CategoryLevel_Threshold</th>
<th>amount in product (mg)</th>
<th>Application</th>
<th>ppm in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Homogeneous Material</td>
<td>Material Group</td>
<td>UdmF</td>
<td>Mass</td>
<td>UoM</td>
</tr>
<tr>
<td>-----------------------</td>
<td>----------------</td>
<td>------</td>
<td>------</td>
<td>-----</td>
</tr>
<tr>
<td>Die</td>
<td>Other inorganic materials</td>
<td>0.370</td>
<td>ng supplier</td>
<td>wire</td>
</tr>
<tr>
<td>Die</td>
<td>Other inorganic materials</td>
<td>0.003</td>
<td>mg supplier</td>
<td>wire</td>
</tr>
<tr>
<td>Die</td>
<td>Other inorganic materials</td>
<td>0.003</td>
<td>mg supplier</td>
<td>wire</td>
</tr>
<tr>
<td>Die</td>
<td>Other inorganic materials</td>
<td>0.003</td>
<td>mg supplier</td>
<td>wire</td>
</tr>
<tr>
<td>Die</td>
<td>Other inorganic materials</td>
<td>0.002</td>
<td>mg supplier</td>
<td>wire</td>
</tr>
<tr>
<td>Die</td>
<td>Other inorganic materials</td>
<td>0.001</td>
<td>mg supplier</td>
<td>wire</td>
</tr>
<tr>
<td>Die</td>
<td>Other inorganic materials</td>
<td>0.002</td>
<td>mg supplier</td>
<td>wire</td>
</tr>
<tr>
<td>Die</td>
<td>Other inorganic materials</td>
<td>0.002</td>
<td>mg supplier</td>
<td>alloy</td>
</tr>
<tr>
<td>Die</td>
<td>Other inorganic materials</td>
<td>0.002</td>
<td>mg supplier</td>
<td>alloy</td>
</tr>
<tr>
<td>Die</td>
<td>Other inorganic materials</td>
<td>0.002</td>
<td>mg supplier</td>
<td>alloy</td>
</tr>
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<td>Die</td>
<td>Other inorganic materials</td>
<td>0.003</td>
<td>mg supplier</td>
<td>alloy</td>
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<td>0.002</td>
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<td>0.002</td>
<td>mg supplier</td>
<td>alloy</td>
</tr>
<tr>
<td>Die</td>
<td>Other inorganic materials</td>
<td>0.001</td>
<td>mg supplier</td>
<td>alloy</td>
</tr>
</tbody>
</table>

**Material Composition Declaration**

<table>
<thead>
<tr>
<th>Material Group</th>
<th>Substance Category</th>
<th>Substance</th>
<th>CAS</th>
<th>Exempt</th>
<th>Mass</th>
<th>UoM</th>
<th>Concentration in homogeneous material (ppm)</th>
<th>Concentration in product (ppm)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Bonding Wire</td>
<td>Other inorganic materials</td>
<td>0.001</td>
<td>mg supplier</td>
<td>wire</td>
<td>Copper (Cu)</td>
<td>7440-50-8</td>
<td>0.001</td>
<td>mg supplier</td>
</tr>
<tr>
<td>Bonding Wire</td>
<td>Other inorganic materials</td>
<td>0.001</td>
<td>mg supplier</td>
<td>wire</td>
<td>Copper (Cu)</td>
<td>7440-50-8</td>
<td>0.001</td>
<td>mg supplier</td>
</tr>
<tr>
<td>Encapsulation</td>
<td>Other Organic Material</td>
<td>0.001</td>
<td>mg supplier</td>
<td>glue</td>
<td>Palladium (Pd)</td>
<td>7440-05-3</td>
<td>0.001</td>
<td>mg supplier</td>
</tr>
<tr>
<td>Encapsulation</td>
<td>Other Organic Material</td>
<td>0.001</td>
<td>mg supplier</td>
<td>glue</td>
<td>Bis(α,α-dimethylbenzyl) peroxide</td>
<td>80-43-3</td>
<td>0.001</td>
<td>mg supplier</td>
</tr>
<tr>
<td>Encapsulation</td>
<td>Other Organic Material</td>
<td>0.001</td>
<td>mg supplier</td>
<td>glue</td>
<td>Silver (Ag)</td>
<td>7440-22-4</td>
<td>0.001</td>
<td>mg supplier</td>
</tr>
<tr>
<td>Encapsulation</td>
<td>Other Organic Material</td>
<td>0.001</td>
<td>mg supplier</td>
<td>glue</td>
<td>methylene diacrylate</td>
<td>42594-17-2</td>
<td>0.001</td>
<td>mg supplier</td>
</tr>
<tr>
<td>Encapsulation</td>
<td>Other Organic Material</td>
<td>0.001</td>
<td>mg supplier</td>
<td>glue</td>
<td>Dicyclopentenyloxyethyl methacrylate</td>
<td>68586-19-6</td>
<td>0.001</td>
<td>mg supplier</td>
</tr>
<tr>
<td>Encapsulation</td>
<td>Other Organic Material</td>
<td>0.001</td>
<td>mg supplier</td>
<td>glue</td>
<td>Polymer of Polybutadiene + Anhydride resins</td>
<td>Proprietary</td>
<td>0.001</td>
<td>mg supplier</td>
</tr>
<tr>
<td>Encapsulation</td>
<td>Other Organic Material</td>
<td>0.001</td>
<td>mg supplier</td>
<td>glue</td>
<td>carbon black</td>
<td>1333-86-4</td>
<td>0.001</td>
<td>mg supplier</td>
</tr>
</tbody>
</table>

**Connections coating**

<table>
<thead>
<tr>
<th>Supplier</th>
<th>Substance Category</th>
<th>Substance</th>
<th>CAS</th>
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<tbody>
<tr>
<td>Wire</td>
<td>Other inorganic materials</td>
<td>0.001</td>
<td>mg supplier</td>
<td>wire</td>
<td>Copper (Cu)</td>
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